

#25/D (1st)  
F-BELL  
2.26.03

**THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the application of:  
Jonathan Meigs, et al.

Docket: 30-4590 (4950)

Serial Number: 09/361,458

Group Art Unit: 2832

Filed: July 27, 1999

Examiner: Karl Easthom

For: COMPOSITION AND METHOD FOR MANUFACTURING INTEGRAL  
RESISTORS IN PRINTED CIRCUIT BOARDS

**NOTICE: THIS APPLICATION IS UNDER FINAL REJECTION**

**AMENDMENT**

Commissioner for Patents  
Washington, D.C. 20231

**FAX RECEIVED**

FEB 24 2003

TECHNOLOGY CENTER 2800

Sir:

In response to the Office Action mailed November 22, 2002, please amend the above  
identified patent application as follows:

In the claims:

**CLEAN COPY OF AMENDED CLAIMS**

11. (Amended) A multi-layer foil comprising a copper metal layer having a shiny surface, and an electrically resistive composite material layer on the copper metal layer shiny surface wherein the electrically resistive composite material layer includes from about 0.01 to about 99.9 area % of nickel and from about 0.01 to about 99.9 area % of particles of alumina, which multi-layer foil is formed by codepositing the alumina and the nickel onto the copper metal layer shiny surface by electrodeposition and wherein the electrically resistive composite material has a resistivity of from about 1 to about 10,000 ohms/square.